



10/B

10-18-02

500.39590X00

Moriishi

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: MIYAKI et al.
Serial No.: 09/785,452
Filed: February 20, 2001
For: SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE
AND METHOD OF MANUFACTURING THE SAME
Group: 2827
Examiner: L. Cruz

AMENDMENT

Assistant Commissioner
for Patents
Washington, D.C. 20231

October 7, 2002

Sir:

In response to the Office Action dated June 6, 2002, the period of response
for which extension is requested by the attached Petition for Extension of Time,
please amend the above-identified application as follows:

In the Claims:

Please cancel claims 1, 8 and 11-15 without prejudice.

Please amend claims 2-7, 9 and 10 as follows:

2. (Amended) A semiconductor integrated circuit device comprising:

a conductive connecting member;

a connected member in which a metal layer including a palladium layer is
provided at a first portion to which said connecting member is connected, and an

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